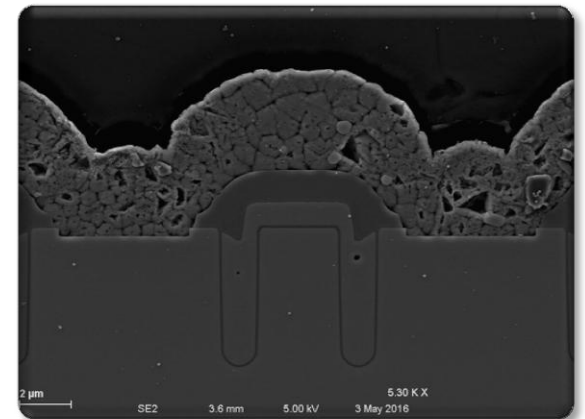
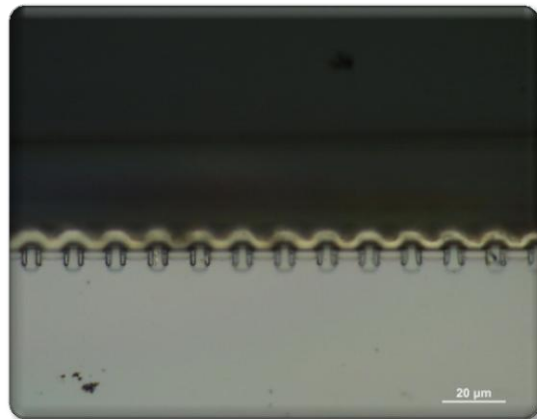


# SIGC54T65R3E

IGBT Bare Die with 650V Trench & Field Stop Technology



## Product Analysis Report

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